

BILL OF MATERIALS for TAS5624ADDVEVM (RevB)

May 6, 2013

| ITEM | MANU PART NUM | MANU | QTY | REF DESIGNATORS | DESCRIPTION |
|------|--------------------|-----------------------|-----|---|--|
| 1 | TAS5624ADDV | TEXAS INSTRUMENTS | 1 | U1 | 125W-STEREO/250W-MONO PUREPATH DIGITAL AMP HTSSOP44-DDV ROHS |
| 2 | TAS5558DCA | TEXAS INSTRUMENTS | 1 | U2 | 8 CHAN HD AUDIO PROCESSOR W/PWM OUTPUTS HTSSOP56-DCA ROHS |
| 3 | TPS3825-33DBVT | TEXAS INSTRUMENTS | 1 | U3 | PROCESSOR SUPERVISORY CIRCUITS 2.93V 200ms SOT23-DBV5 ROHS |
| 4 | TLV1117-33CDCYR | TEXAS INSTRUMENTS | 1 | VR1 | VOLT REG LDO 3.3V 800mA SOT223-DCY ROHS |
| 5 | 2N7002 | FAIRCHILD | 4 | Q1,Q2,Q3,Q4 | N-FET 60V 115mA 200mW 7.5 OHM@10V SOT23-DBV3 ROHS |
| 6 | SML-LXT0805SRW-TR | LUMEX OPTO | 3 | 125C, FAULT, AMP_RESET | LED, RED 2.0V SMD0805 ROHS |
| 7 | SML-LXT0805YW-TR | LUMEX OPTO | 1 | CLIP | LED, YELLOW 2.0V SMD0805 ROHS |
| 8 | EEU-FC1C470 | PANASONIC | 4 | C1,C51,C73, C75 | CAP 47UF 16V RAD ALUM ELEC FC ROHS |
| 9 | GRM188R71C104KA01D | MURATA | 17 | C2, C3, C4, C7, C32, C50, C52, C53, C59, C60, C62, C63, C64, C65, C74, C76, C77 | CAP SMD0603 CERM 0.1UF 16V 10% X7R ROHS |
| 10 | C1608X7R1C105K | TDK | 2 | C5,C6 | CAP SMD0603 CERM 1.0UF 16V 10% X7R ROHS |
| 11 | GRM21BR71H105KA12L | MURATA | 5 | C8,C9,C10,C11,C71 | CAP SMD0805 CERM 1.0UF 50V 10% X7R ROHS |
| 12 | EEU-FC1H102 | PANASONIC | 2 | C12,C14 | CAP ALUM ELEC FC RADIAL 1000UF 50V 20% ROHS |
| 13 | GRM188R71H333KA61D | MURATA | 4 | C16,C17,C18,C19 | CAP SMD0603 CERM 0.033UF 50V 10% X7R ROHS |
| 14 | MKP4 -.68/250/20 | WIMA | 4 | C20,C23,C26,C29 | CAP POLYPRO FILM MKP4 0.68UF 250V 20% ROHS |
| 15 | C1206C102K1RACTU | KEMET | 4 | C21,C24,C27,C30 | CAP SMD1206 CERM 1000PFD 100V 1% C0G ROHS |
| 16 | GRM21BR72A103KA01L | MURATA | 5 | C22,C25,C28,C31,C70 | CAP SMD0805 CERM 0.01UF 100V 10% X7R ROHS |
| 17 | GRM188R71H472KA01D | MURATA | 2 | C54,C55 | CAP SMD0603 CERM 4700PFD 50V 10% X7R ROHS |
| 18 | GRM188R71C473KA01D | MURATA | 2 | C56,C57 | CAP SMD0603 CERM 0.047UF 16V 10% ROHS |
| 19 | GRM21BR61C106KE15L | MURATA | 3 | C58,C61,C66 | CAP SMD0805 CERM 10UF 16V 10% X5R ROHS |
| 20 | UKZ1H470MPPM | NICHICON | 1 | C72 | CAP ALUM ELEC KZ RADIAL 47UF 50V 20% ROHS |
| 21 | ERJ-3GEYJ3R3V | PANASONIC | 8 | R1, R7, R8, R9, R10, R11, R14, R60 | RESISTOR SMD0603 3.3 OHMS 5% 1/10W ROHS |
| 22 | RC0603FR-0730KL | YAGEO | 1 | R2 | RESISTOR SMD0603 THICK FILM 30.0K 1% 1/10W ROHS |
| 23 | ERJ-3GEYJ473V | PANASONIC | 1 | R3 | RESISTOR SMD0603 47K OHMS 5% 1/10W ROHS |
| 24 | CRCW0603100RFKEA | VISHAY | 3 | R4,R5,R6 | RESISTOR SMD0603 100 OHM 1/10W 1% ROHS |
| 25 | RMCF0402ZT0R00 | STACKPOLE ELECTRONICS | 2 | R12,R13 | ZERO OHM JUMPER SMT 0402 0 OHM 1/16W,5% ROHS |
| 26 | ERJ-3EKF1002V | PANASONIC | 14 | R20, R21, R22, R23, R24, R25, R26, R41, R42, R43, R44, R45, R46, R47 | RESISTOR SMD0603 10.0K 1% THICK FILM 1/10W ROHS |
| 27 | ERJ-3GEYJ470V | PANASONIC | 19 | R27, R28, R29, R30, R31, R32, R33, R34, R35, R36, R37, R38, R39, R40, R54, R55, R56, R57, R58 | RESISTOR SMD0603 47 OHMS 5% 1/10W ROHS |
| 28 | ERJ-3GEYJ471V | PANASONIC | 2 | R48,R49 | RESISTOR SMD0603 470 OHMS 5% 1/10W ROHS |
| 29 | ERJ-3GEYJ1R0V | PANASONIC | 1 | R50 | RESISTOR SMD0603 1.0 OHMS 1% THICK FILM 1/10W ROHS |
| 30 | ERJ-3GEYJ472V | PANASONIC | 4 | R61,R62,R63,R65 | RESISTOR SMD0603 4.7K OHMS 5% 1/10W ROHS |
| 31 | RMCF0603FT15K0 | STACKPOLE ELECTRONICS | 1 | R52 | RESISTOR SMD0603 15.0K OHMS 1% 1/10W ROHS |
| 32 | RC0603FR-0718KL | YAGEO | 1 | R53 | RESISTOR SMD0603 THICK FILM 18.0K OHMS 1% 1/10W ROHS |
| 33 | MA5173-AE | COIL CRAFT | 4 | L1, L2, L3, L4 | SHIELDED POWER INDUCTOR 7uH 12A ROHS |
| 34 | N2526-6002-RB | 3M | 1 | J1 | HEADER SHROUDED 100LS MALE GOLD 2X13 PINS ROHS |
| 35 | PBC02SAAN | SULLINS | 1 | JP1 | HEADER THRU MALE 2 PIN 100LS GOLD ROHS |
| 36 | PBC03SAAN | SULLINS | 3 | C,D,M3 | HEADER THRU MALE 3 PIN 100LS GOLD ROHS |
| 37 | G12AP-RO | NKK | 1 | S1 | SWITCH THRU SPDT STRAIGHT ULTRA MINIATURE ROHS |
| 38 | 5018-0 | POMONA | 3 | GND, LOUT-, ROUT- | BINDING POST, BLACK 60V 30A GOLD ROHS |
| 39 | 5018-2 | POMONA | 3 | PVDD, LOUT+, ROUT+ | BINDING POST, RED 60V 30A GOLD ROHS |

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| 40 | SPC02SYAN | SULLINS | 4 | JP1,C(1-2),D(1-2),M3(1-2) | SHUNT, BLACK AU FLASH 0.100LS |
| 41 | ATSTI1OP-519-C1-R1 | ATS | 1 | HEAT SINK (U1) | HEATSINK ALUMINUM ATS 36x78mm 36.8mm PITCH ROHS |
| 42 | 92000A118 | McMaster-Carr | 2 | HEAT SINK SCREWS | PHILIPS PANHEAD SCREW M3x8mm STAINLESS STEEL ROHS |
| 43 | 92148A150 | McMaster-Carr | 2 | HEAT SINK WASHERS | SPLIT WASHER M3 STAINLESS STEEL ROHS |
| 44 | 94868A178 | McMaster-Carr | 4 | STANDOFFS | STANDOFF M3x25mm 4.5mm DIA HEX STAINLESS STEEL F-F ROHS |
| 45 | 92000A118 | McMaster-Carr | 4 | STANDOFF SCREWS | PHILIPS PANHEAD SCREW M3x8mm STAINLESS STEEL ROHS |
| 46 | 92148A150 | McMaster-Carr | 4 | STANDOFF WASHERS | SPLIT WASHER M3 STAINLESS STEEL ROHS |

| CABLE ASSEMBLY (1 each per EVM) | | | | | |
|---------------------------------|------------|-----------------|---|----|--|
| CA1 | 1658621-6 | TE CONNECTIVITY | 1 | NA | IDC SOCKET FEMALE 26 PIN 0.1" PITCH ROHS |
| CA2 | 499252-3 | TE CONNECTIVITY | 1 | NA | 26 POSITION STRAIN RELIEF FOR AKC26H-ND ROHS |
| CA3 | AE26M-5-ND | ASSMANN WSW | 1 | NA | 26 POSITION RIBBON CABLE 0.05" PITCH ROHS |

| CONTROLLER BOARD (1 each per EVM) | | | | | |
|-------------------------------------|--|--|--|--|--|
| InputUsbBoard3_RevA (Edge #6527708) | | | | | |

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| TOTAL | 167 |
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| X1 | DO NOT POPULATE | 4 | CR1, CR2, CR3, CR4 | |
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| SPECIAL NOTES TO THIS BILL OF MATERIALS | |
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| SN1 | These assemblies are ESD sensitive, ESD precautions shall be observed. |
| SN2 | These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable. |
| SN3 | These assemblies must comply with workmanship standards IPC-A-610 Class 2. |

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